



Material Content Data Sheet



Sales Product Name	ESD8V0R1B-02LRH E6327				Issued		30. January 2015	
MA#	MA000368734							
Package	PG-TSLP-2-7				Weight*		0.51 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.07		679	
	noble metal	gold	7440-57-5	0.001	0.26		2629	
	inorganic material	silicon	7440-21-3	0.017	3.21	3.54	32096	35404
leadframe	non noble metal	nickel	7440-02-0	0.100	19.49	19.49	194913	194913
wire	noble metal	gold	7440-57-5	0.006	1.11	1.11	11138	11138
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		360	
	organic material	carbon black	1333-86-4	0.004	0.72		7210	
	plastics	epoxy resin	-	0.050	9.73		97336	
	inorganic material	silicondioxide	60676-86-0	0.317	61.61	72.10	616100	721006
leadfinish	noble metal	gold	7440-57-5	0.010	1.88	1.88	18755	18755
plating	noble metal	gold	7440-57-5	0.010	1.88	1.88	18784	18784
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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